INTEGRATED CIRCUITS



Product specification Supersedes data of 1995 Aug 17 IC23 Data Handbook

1998 Feb 27



Philips Semiconductors

74ABT16646 74ABTH16646

FEATURES

- Independent registers for A and B buses
- Multiple Vcc and GND pins minimize switching noise
- Live insertion/extraction permitted
- Power–up 3-State
- Power–up reset
- Multiplexed real-time and stored data
- Outputs sink 64mA and source 32mA
- Latch-up protection exceeds 500mA per JEDEC Std 17
- 74ABTH16646 incorporates bus-hold data inputs which eliminate the need for external pull-up resistors to hold unused inputs
- ESD protection exceeds 2000V per MIL STD 883 Method 3015 and 200V per Machine Model

DESCRIPTION

The 74ABT16646 high–performance BiCMOS device combines low static and dynamic power dissipation with high speed and high output drive.

The 74ABT16646 16-bit transceiver/register consists of two sets of bus transceiver circuits with 3-State outputs, D-type flip-flops, and control circuitry arranged for multiplexed transmission of data directly from the input bus or from the internal registers. Data on the A or B bus will be clocked into the registers as the appropriate clock pin goes High. Output Enable ($n\overline{OE}$) and Direction (nDIR) pins are provided to control the transceiver function. In the transceiver mode, data present at the high impedance port may be stored in either the A or B register or both.

The select (nSAB, nSBA) pins determine whether data is stored or transferred through the device in real-time. The nDIR determines which bus will receive data when the n \overline{OE} is active Low. In the isolation mode (n \overline{OE} = High), data from Bus A may be stored in the B register and/or data from Bus B may be stored in the A register. When an output function is disabled, the input function is still enabled and may be used to store and transmit data. Only one of the two buses, A or B may be driven at a time.

Two options are available, 74ABT16646 which does not have the bus-hold feature and 74ABTH16646 which incorporates the bus-hold feature.

QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS T _{amb} = 25°C; GND = 0V	TYPICAL	UNIT
t _{PLH} t _{PHL}	Propagation delay nAx to nBx	$C_L = 50 pF; V_{CC} = 5V$	3.3 2.7	ns
C _{IN}	Input capacitance	$V_I = 0V \text{ or } V_{CC}$	3	pF
C _{I/O}	I/O capacitance	$V_{O} = 0V$ or V_{CC} ; 3-State	7	pF
1		Outputs disabled; $V_{CC} = 5.5V$	550	μA
ICCZ	Quiescent supply current	Outputs low; $V_{CC} = 5.5V$	9	mA

ORDERING INFORMATION

PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	DWG NUMBER
56-Pin Plastic SSOP Type III	–40°C to +85°C	74ABT16646 DL	BT16646 DL	SOT371-1
56-Pin Plastic TSSOP Type II	–40°C to +85°C	74ABT16646 DGG	BT16646 DGG	SOT364-1
56-Pin Plastic SSOP Type III	–40°C to +85°C	74ABTH16646 DL	BH16646 DL	SOT371-1
56-Pin Plastic TSSOP Type II	–40°C to +85°C	74ABTH16646 DGG	BH16646 DGG	SOT364-1

PIN DESCRIPTION

PIN NUMBER	SYMBOL	NAME AND FUNCTION
2, 55, 27, 30	1CPAB, 1CPBA, 2CPAB, 2CPBA	Clock input A to B / Clock input B to A
3, 54, 26, 31	1SAB, 1SBA, 2SAB, 2SBA	Select input A to B / Select input B to A
1, 28	1DIR, 2DIR	Direction control inputs
5, 6, 8, 9, 10, 12, 13, 14 15, 16, 17, 19, 20, 21, 23, 24	1A0 – 1A7, 2A0 – 2A7	Data inputs/outputs (A side)
52, 51, 49, 48, 47, 45, 44, 43 42, 41, 40, 38, 37, 36, 34, 33	1B0 – 1B7, 2B0 – 2B7	Data inputs/outputs (B side)
56, 29	10E, 20E	Output enable inputs
4, 11, 18, 25, 32, 39, 46, 53	GND	Ground (0V)
7, 22, 35, 50	V _{CC}	Positive supply voltage

74ABT16646 74ABTH16646

PIN CONFIGURATION

1DIR 1 56 1OE	
1CPAB 2 55 1CPBA	
1SAB 3 54 1SBA	
GND 4 53 GND	
1A0 5 1B0	
1A1 6 51 1B1	
V _{CC} 7 50 V _{CC}	
1A2 8 49 1B2	
1A3 9 48 1B3	
1A4 10 47 1B4	
GND 11 46 GND	
1A5 12 45 1B5	
1A6 13 44 1B6	
1A7 14 43 1B7	
2A0 15 42 2B0	
2A1 16 41 2B1	
2A2 17 40 2B2	
GND 18 39 GND	
2A3 19 38 2B3	
2A4 20 37 2B4	
2A5 21 36 2B5	
V _{CC} 22 35 V _{CC}	
2A6 23 34 2B6	
2A7 24 33 2B7	
GND 25 32 GND	
2SAB 26 31 2SBA	
2CPAB 27 30 2CPBA	
2DIR 28 29 20E	
SH00026	

FUNCTION TABLE

	INPUTS					DATA I/O		OPERATING MODE
nOE	nDIR	nCPAB	nCPBA	nSAB	nSBA	nAx	nBx	OPERATING MODE
х	х	Ť	Х	х	Х	Input	Unspecified output*	Store A, B unspecified
х	х	х	Ŷ	х	Х	Unspecified output*	Input	Store B, A unspecified
H H	X X	↑ H or L	↑ H or L	X X	X X	Input	Input	Store A and B data Isolation, hold storage
L	L	X X	X H or L	X X	L H	Output	Input	Real time B data to A bus Stored B data to A bus
L	H H	X H or L	X X	L H	X X	Input	Output	Real time A data to B bus Stored A data to B bus

H = High voltage level L = Low voltage level

∠ = Don't care
↑ = Low-to-High clock transition
* The data output function mail

The data output function may be enabled or disabled by various signals at the $n\overline{OE}$ input. Data input functions are always enabled, i.e., data at the bus pins will be stored on every Low-to-High transition of the clock.

74ABT16646 74ABTH16646



LOGIC SYMBOL



74ABT16646 74ABTH16646



The following examples demonstrate the four fundamental bus-management functions that can be performed with the 74ABT16646.

74ABT16646 74ABTH16646



LOGIC DIAGRAM

ABSOLUTE MAXIMUM RATINGS^{1, 2}

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V _{CC}	DC supply voltage		-0.5 to +7.0	V
I _{IK}	DC input diode current	V ₁ < 0	-18	mA
VI	DC input voltage ³		-1.2 to +7.0	V
I _{OK}	DC output diode current	V _O < 0	-50	mA
V _{OUT}	DC output voltage ³	output in Off or High state	-0.5 to +5.5	V
	DC output current	output in Low state	128	mA
IOUT		output in High state	-64	mA
T _{stg}	Storage temperature range		-65 to 150	°C

NOTES:

1. Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

2. The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability. The maximum junction temperature of this integrated circuit should not exceed 150°C.

3. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

74ABT16646 74ABTH16646

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	LIM	UNIT	
		MIN	MAX	
V _{CC}	DC supply voltage	4.5	5.5	V
VI	Input voltage	0	V _{CC}	V
V _{IH}	High-level input voltage	2.0		V
V _{IL}	Low-level Input voltage		0.8	V
I _{OH}	High-level output current		-32	mA
I _{OL}	Low-level output current		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0	10	ns/V
T _{amb}	Operating free-air temperature range	-40	+85	°C

DC ELECTRICAL CHARACTERISTICS

				LIMITS					
SYMBOL PARAMETER		TEST CONDITIONS		mb = +25	5°C	T _{amb} = to +	₌ –40°C 85°C		
			MIN	TYP	MAX	MIN	MAX	1	
V _{IK}	Input clamp voltage	$V_{CC} = 4.5V; I_{IK} = -18mA$		-0.9	-1.2		-1.2	V	
		V_{CC} = 4.5V; I_{OH} = -3mA; V_I = V_{IL} or V_{IH}	2.5	2.9		2.5		V	
V _{OH}	High-level output voltage	V_{CC} = 5.0V; I_{OH} = -3mA; V_I = V_{IL} or V_{IH}	3.0	3.4		3.0		V	
		V_{CC} = 4.5V; I_{OH} = -32mA; V_I = V_{IL} or V_{IH}	2.0	2.4		2.0		V	
V _{OL}	Low-level output voltage	V_{CC} = 4.5V; I_{OL} = 64mA; V_I = V_{IL} or V_{IH}		0.35	0.55		0.55	V	
V _{RST}	Power-up output voltage ³	V_{CC} = 5.5V; I_{O} = 1mA; V_{I} = GND or V_{CC}		0.13	0.55		0.55	V	
łı	Input leakage current	$V_{CC} = 5.5V; V_I = GND \text{ or } 5.5V$ Contriputs		±0.01	±1.0		±1.0	μΑ	
		$V_{CC} = 4.5V; V_{I} = 0.8V$	35			35			
I _{HOLD}	Bus Hold current A or B Ports ⁵ 74ABTH16646	$V_{CC} = 4.5V; V_I = 2.0V$ -				-75		μA	
		$V_{CC} = 5.5V; V_{I} = 0 \text{ to } 5.5V$	±800						
I _{OFF}	Power-off leakage current	$V_{CC} = 0.0V; V_{O} = 4.5V; V_{I} = 0.0V \text{ or } 5.5V$		±2.0	±100		±100	μΑ	
I _{PU/PD}	Power-up/down 3-State output current ⁴	$V_{CC} = 2.1V$; $V_{O} = 0.0V$ or V_{CC} ; $V_{I} = GND$ or V_{CC} ; $OE/\overline{OE} = X$		±1.0	±50		±50	μΑ	
I _{IH} + I _{OZH}	3-State output High current	V_{CC} = 5.5V; V_{O} = 5.5V; V_{I} = V_{IL} or V_{IH}		1.0	10		10	μΑ	
I _{IL} + I _{OZL}	3-State output Low current	V_{CC} = 5.5V; V_O = 0.0V; V_I = V_{IL} or V_{IH}		-1.0	-10		-10	μΑ	
ICEX	Output High leakage current	V_{CC} = 5.5V; V_{O} = 5.5V; V_{I} = GND or V_{CC}		5.0	50		50	μA	
Ι _Ο	Output current ¹	$V_{CC} = 5.5 V; V_{O} = 2.5 V$	-50	-80	-180	-50	-180	mA	
ICCH		V_{CC} = 5.5V; Outputs High, V _I = GND or V_{CC}		0.55	2		2	mA	
I _{CCL}	Quiescent supply current	V_{CC} = 5.5V; Outputs Low, V_{I} = GND or V_{C}	c	9	19		19	mA	
I _{CCZ}		V_{CC} = 5.5V; Outputs 3–State; V _I = GND or V _{CC}		0.55	2		2	mA	
ΔI_{CC}	Additional supply current per input pin ² 74ABT16646	V_{CC} = 5.5V; one input at 3.4V, other inputs at V_{CC} or GND		5.0	50		50	μΑ	
ΔI_{CC}	Additional supply current per input pin ² 74ABTH16646	V_{CC} = 5.5V; one input at 3.4V, other inputs at V_{CC} or GND		200	500		500	μΑ	

NOTES:

1. Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

2. This is the increase in supply current for each input at 3.4V.

3. For valid test results, data must not be loaded into the flip-flops (or latches) after applying the power. 4. This parameter is valid for any V_{CC} between 0V and 2.0V, with a transition time of up to 100msec. From $V_{CC} = 21.V$ to $V_{CC} = 5V \pm 10\%$ a transition time of up to 100µsec is permitted.

5. This is the bus hold overdrive current required to force the input to the opposite logic state.

74ABT16646 74ABTH16646

AC CHARACTERISTICS GND = 0V, t_R = t_F = 2.5ns, C_L = 50pF, R_L = 500 Ω

					LIMITS			
SYMBOL	PARAMETER	WAVEFORM	r	ا _{amb} = +25° V _{CC} = +5.0	с /	+8	= -40 to 5°C .0V ±0.5V	UNIT
			MIN	TYP	MAX	MIN	MAX	
f _{MAX}	Maximum clock frequency	1	125			125		MHz
t _{PLH} t _{PHL}	Propagation delay nCPAB to nBx or nCPBA to nAx	1	1.5 1.5	3.3 2.7	4.0 4.1	1.5 1.5	4.9 4.7	ns
t _{PLH} t _{PHL}	Propagation delay nAx to nBx or nBx to nAx	2	1.0 1.0	2.3 2.0	3.2 4.1	1.0 1.0	3.9 4.6	ns
t _{PLH} t _{PHL}	Propagation delay nSAB to nBx or nSBA to nAx	2, 3	1.0 1.0	3.1 2.7	4.3 4.3	1.0 1.0	5.0 5.0	ns
t _{PZH} t _{PZL}	Output enable time nOE to nAx or nBx	5, 6	1.0 1.5	3.2 3.3	4.6 4.9	1.0 1.5	5.5 5.7	ns
t _{PHZ} t _{PLZ}	Output disable time nOE to nAx or nBx	5, 6	1.5 1.5	3.5 2.7	4.9 4.1	1.5 1.5	5.4 4.5	ns
t _{PZH} t _{PZL}	Output enable time nDIR to nAx or nBx	5, 6	1.0 1.5	4.1 4.3	4.8 4.8	1.0 1.5	5.4 5.6	ns
t _{PHZ} t _{PLZ}	Output disable time nDIR to nAx or nBx	5, 6	2.0 1.5	3.6 2.7	5.7 5.1	2.0 1.5	6.7 5.9	ns

AC SETUP REQUIREMENTS

GND = 0V, $t_R = t_F = 2.5$ ns, $C_L = 50$ pF, $R_L = 500\Omega$

				LIN	NITS	
SYMBOL	PARAMETER	WAVEFORM	T _{amb} = V _{CC} =	= +25°C = +5.0V	T _{amb} = -40 to +85°C V _{CC} = +5.0V ±0.5V	UNIT
			MIN	TYP	MIN	
t _s (H) t _s (L)	Setup time nAx to nCPAB, nBx to nCPBA	4	2.0 1.5	1.0 0.8	2.0 1.5	ns
t _h (H) t _h (L)	Hold time nAx to nCPAB, nBx to nCPBA	4	1.5 1.0	0.0 0.7	1.5 1.0	ns
t _w (H) t _w (L)	Pulse width, High or Low nCPAB or nCPBA	1	4.5 3.0	2.5 2.0	4.5 3.0	ns

AC WAVEFORMS

 $V_{M} = 1.5V, V_{IN} = GND \text{ to } 3.0V$



Waveform 1. Propagation Delay, Clock Input to Output, Clock Pulse Width, and Maximum Clock Frequency





74ABT16646 74ABTH16646

AC WAVEFORMS (Continued)



Waveform 3. Propagation Delay, nSBA to nAx or nSAB to nBx



Waveform 4. Data Setup and Hold Times



Waveform 5. 3–State Output Enable Time to High Level and Output Disable Time from High Level



Waveform 6. 3–State Output Enable Time to Low Level and Output Disable Time from Low Level



R_L = Load resistor; see AC CHARACTERISTICS for value.

- C_L = Load capacitance includes jig and probe capacitance; see AC CHARACTERISTICS for value.
- $\label{eq:RT} R_T = \begin{tabular}{ll} Termination resistance should be equal to Z_{OUT} of pulse generators. \end{tabular}$

FAMILY	INPUT PULSE REQUIREMENTS					
FAMILT	Amplitude	e Rep. Rate t _M		t _R	t _F	
74ABT/H16	3.0V	1MHz	500ns	2.5ns	2.5ns	

SA00018

1998 Feb 27

TEST CIRCUIT AND WAVEFORMS

74ABT16646 74ABTH16646



74ABT16646 74ABTH16646



74ABT16646 74ABTH16646

Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
Preliminary specification	Qualification	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make chages at any time without notice in order to improve design and supply the best possible product.
Product specification	Production	This data sheet contains final specifications. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.

[1] Please consult the most recently issued datasheet before initiating or completing a design.

Definitions

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information — Applications that are described herein for any of these products are for illustrative purposes only. Philips Semiconductors make no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

Disclaimers

Life support — These products are not designed for use in life support appliances, devices or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips Semiconductors customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips Semiconductors for any damages resulting from such application.

Right to make changes — Philips Semiconductors reserves the right to make changes, without notice, in the products, including circuits, standard cells, and/or software, described or contained herein in order to improve design and/or performance. Philips Semiconductors assumes no responsibility or liability for the use of any of these products, conveys no license or title under any patent, copyright, or mask work right to these products, and makes no representations or warranties that these products are free from patent, copyright, or mask work right infringement, unless otherwise specified.

Philips Semiconductors 811 East Arques Avenue P.O. Box 3409 Sunnyvale, California 94088–3409 Telephone 800-234-7381 © Copyright Philips Electronics North America Corporation 1998 All rights reserved. Printed in U.S.A.

print code

Document order number:

Date of release: 05-96 9397-750-03498

Let's make things better.



PHILIPS